

- **High Capacitive-Drive Capability**
- 'ALS805A Has Typical Delay Time of 4.2 ns ($C_L = 50 \text{ pF}$) and Typical Power Dissipation of 4.2 mW Per Gate
- 'AS805B Has Typical Delay Time of 2.6 ns ($C_L = 50 \text{ pF}$) and Typical Power Dissipation of 12 mW Per Gate
- **Package Options Include Plastic Small-Outline (DW) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) 300-mil DIPs**

description

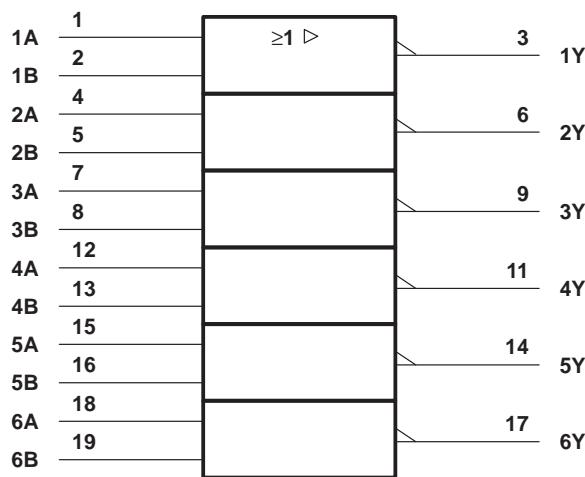
These devices contain six independent 2-input NOR drivers. They perform the Boolean functions $Y = A + \bar{B}$ or $Y = \bar{A} \bullet \bar{B}$ in positive logic.

The SN54ALS805A and SN54AS805B are characterized for operation over the full military temperature range of -55°C to 125°C . The SN74ALS805A and SN74AS805B are characterized for operation from 0°C to 70°C .

FUNCTION TABLE
(each driver)

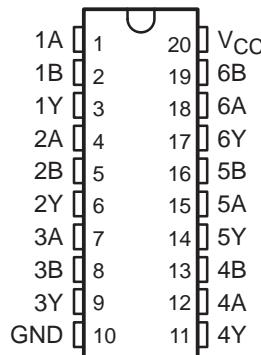
INPUTS		OUTPUT
A	B	Y
H	X	L
X	H	L
L	L	H

logic symbol†

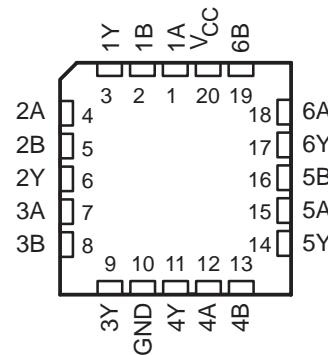


† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

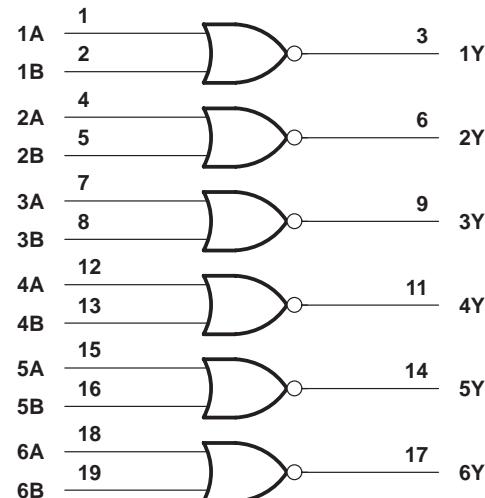
SN54ALS805A, SN54AS805B . . . J PACKAGE
SN74ALS805A, SN74AS805B . . . DW OR N PACKAGE
(TOP VIEW)



SN54ALS805A, SN54AS805B . . . FK PACKAGE
(TOP VIEW)



logic diagram (positive logic)



SN54ALS805A, SN54AS805B, SN74ALS805A, SN74AS805B HEX 2-INPUT NOR DRIVERS

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

		SN54ALS805A			SN74ALS805A			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V _{CC}	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
V _{IH}	High-level input voltage		2		2			V
V _{IL}	Low-level input voltage			0.7			0.8	V
I _{OH}	High-level output current			-12			-15	mA
I _{OL}	Low-level output current			12			24	mA
T _A	Operating free-air temperature	-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	SN54ALS805A			SN74ALS805A			UNIT
		MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V_{IK}	$V_{CC} = 4.5 \text{ V}$, $I_I = -18 \text{ mA}$			-1.2			-1.2	V
V_{OH}	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$, $I_{OH} = -0.4 \text{ mA}$	$V_{CC} - 2$			$V_{CC} - 2$			V
	$V_{CC} = 4.5 \text{ V}$	$I_{OH} = -3 \text{ mA}$	2.4	3.2	2.4	3.2		
		$I_{OH} = -12 \text{ mA}$	2					
		$I_{OH} = -15 \text{ mA}$				2		
V_{OL}	$V_{CC} = 4.5 \text{ V}$	$I_{OL} = 12 \text{ mA}$	0.25	0.4	0.25	0.4		V
		$I_{OL} = 24 \text{ mA}$			0.35	0.5		
I_I	$V_{CC} = 5.5 \text{ V}$, $V_I = 7 \text{ V}$			0.1			0.1	mA
I_{IH}	$V_{CC} = 5.5 \text{ V}$, $V_I = 2.7 \text{ V}$			20			20	μA
I_{IL}	$V_{CC} = 5.5 \text{ V}$, $V_I = 0.4 \text{ V}$			-0.1			-0.1	mA
$I_O\$$	$V_{CC} = 5.5 \text{ V}$, $V_O = 2.25 \text{ V}$	-20	-112		-30	-112		mA
I_{CCH}	$V_{CC} = 5.5 \text{ V}$, $V_I = 0$		2	4	2	4		mA
I_{CCI}	$V_{CC} = 5.5 \text{ V}$, $V_I = 4.5 \text{ V}$		8	14	8	14		mA

[‡]All typical values are at $V_{CC} = 5$ V, $T_A = 25^\circ\text{C}$.

§ The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, I_{OS} .

SN54ALS805A, SN54AS805B, SN74ALS805A, SN74AS805B HEX 2-INPUT NOR DRIVERS

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switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 4.5\text{ V to }5.5\text{ V},$ $C_L = 50\text{ pF},$ $R_L = 500\text{ }\Omega,$ $T_A = \text{MIN to MAX}^\dagger$				UNIT	
			SN54ALS805A		SN74ALS805A			
			MIN	MAX	MIN	MAX		
t_{PLH}	A or B	Y	1	12	2	7	ns	
t_{PHL}			1	9	2	8		

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

‡ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions§

		SN54AS805B			SN74AS805B			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V _{CC}	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
V _{IH}	High-level input voltage		2			2		V
V _{IL}	Low-level input voltage			0.8			0.8	V
I _{OH}	High-level output current			-40			-48	mA
I _{OL}	Low-level output current			40			48	mA
T _A	Operating free-air temperature	-55		125	0		70	°C

§ These high sink- or source-current devices are not recommended for use above 40 MHz.

SN54ALS805A, SN54AS805B, SN74ALS805A, SN74AS805B HEX 2-INPUT NOR DRIVERS

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	SN54AS805B			SN74AS805B			UNIT
		MIN	TYPT [†]	MAX	MIN	TYPT [†]	MAX	
V _{IK}	V _{CC} = 4.5 V, I _I = -18 mA			-1.2			-1.2	V
V _{OH}	V _{CC} = 4.5 V to 5.5 V, I _{OH} = -2 mA	V _{CC} - 2			V _{CC} - 2			V
	V _{CC} = 4.5 V	I _{OH} = -3 mA	2.4	3.2	2.4	3.2		
		I _{OH} = -40 mA	2					
		I _{OH} = -48 mA				2		
V _{OL}	V _{CC} = 4.5 V	I _{OL} = 40 mA	0.25	0.5				V
		I _{OL} = 48 mA			0.35	0.5		
I _I	V _{CC} = 5.5 V, V _I = 7 V		0.1			0.1		mA
I _{IH}	V _{CC} = 5.5 V, V _I = 2.7 V			20			20	μA
I _{IL}	V _{CC} = 5.5 V, V _I = 0.4 V			-0.5			-0.5	mA
I _O [‡]	V _{CC} = 5.5 V, V _O = 2.25 V	-50	-200	-50	-200			mA
I _{CCH}	V _{CC} = 5.5 V, V _I = 0		6.5	10	6.5	10		mA
I _{CCL}	V _{CC} = 5.5 V, V _I = 4.5 V		20	32	20	32		mA

[†] All typical values are at V_{CC} = 5 V, T_A = 25°C.

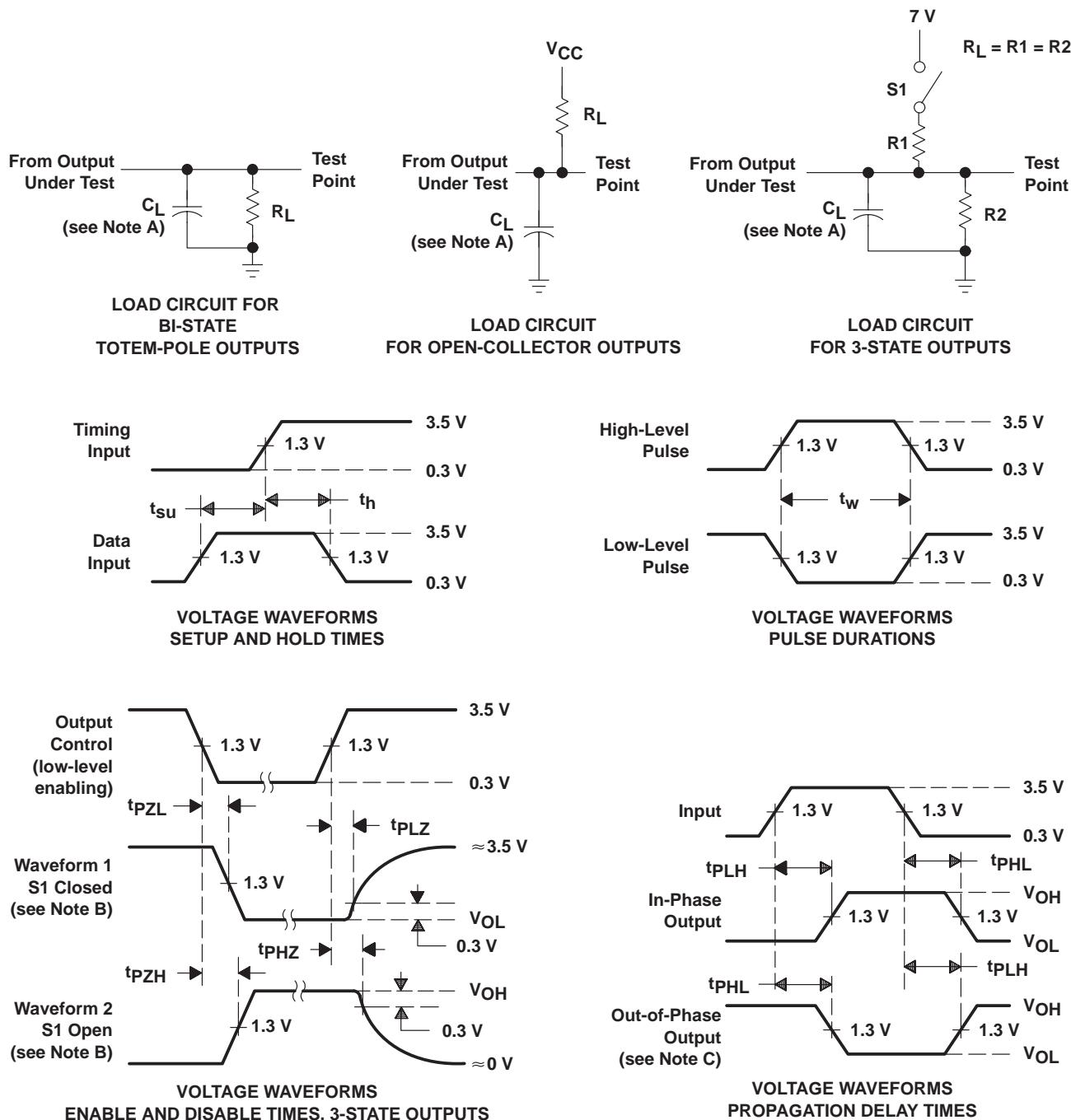
[‡] The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, I_{OS}.

switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 4.5 V to 5.5 V, C _L = 50 pF, R _L = 500 Ω, T _A = MIN to MAX [§]				UNIT	
			SN54AS805B		SN74AS805B			
			MIN	MAX	MIN	MAX		
t _{PLH}	A or B	Y	1	4.8	1	4.3	ns	
			1	4.8	1	4.3		

[§] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

PARAMETER MEASUREMENT INFORMATION
SERIES 54ALS/74ALS AND 54AS/74AS DEVICES



NOTES: A. C_L includes probe and jig capacitance.
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
 D. All input pulses have the following characteristics: PRR \leq 1 MHz, $t_r = t_f = 2$ ns, duty cycle = 50%.
 E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
5962-87794012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
5962-8779401RA	ACTIVE	CDIP	J	20	1	TBD	A42 SNPB	N / A for Pkg Type
5962-8779401SA	ACTIVE	CFP	W	20	1	TBD	A42	N / A for Pkg Type
5962-8869401SA	OBsolete	CFP	W	20		TBD	Call TI	Call TI
SN54ALS805AJ	OBsolete	CDIP	J	20		TBD	Call TI	Call TI
SN54AS805BJ	ACTIVE	CDIP	J	20	1	TBD	A42 SNPB	N / A for Pkg Type
SN74ALS805ADW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS805ADWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS805ADWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS805ADWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS805ADWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS805ADWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS805AN	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74ALS805AN3	OBsolete	PDIP	N	20		TBD	Call TI	Call TI
SN74ALS805ANE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74AS805BDW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS805BDWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS805BDWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS805BDWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS805BDWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS805BDWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS805BN	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74AS805BNE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SNJ54ALS805AFK	OBsolete	LCCC	FK	20		TBD	Call TI	Call TI
SNJ54ALS805AJ	OBsolete	CDIP	J	20		TBD	Call TI	Call TI
SNJ54AS805BFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54AS805BJ	ACTIVE	CDIP	J	20	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54AS805BW	ACTIVE	CFP	W	20	1	TBD	A42	N / A for Pkg Type

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

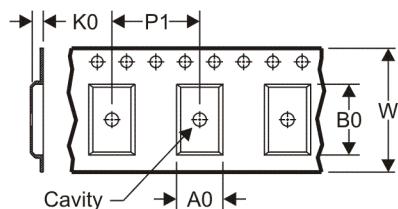
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

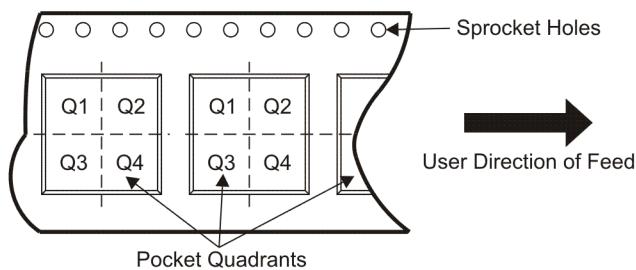
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TAPE AND REEL INFORMATION
REEL DIMENSIONS

TAPE DIMENSIONS


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALS805ADWR	SOIC	DW	20	2000	330.0	24.0	11.0	13.0	3.0	12.0	24.0	Q1
SN74AS805BDWR	SOIC	DW	20	2000	330.0	24.0	11.0	13.0	3.0	12.0	24.0	Q1

TAPE AND REEL BOX DIMENSIONS



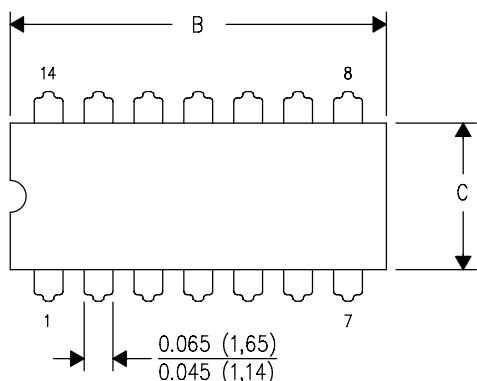
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALS805ADWR	SOIC	DW	20	2000	346.0	346.0	41.0
SN74AS805BDWR	SOIC	DW	20	2000	346.0	346.0	41.0

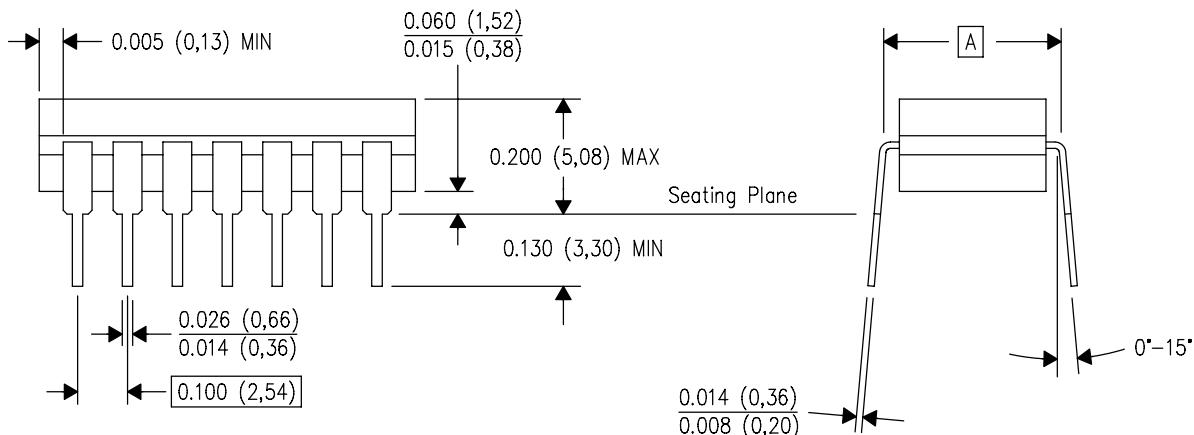
J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)

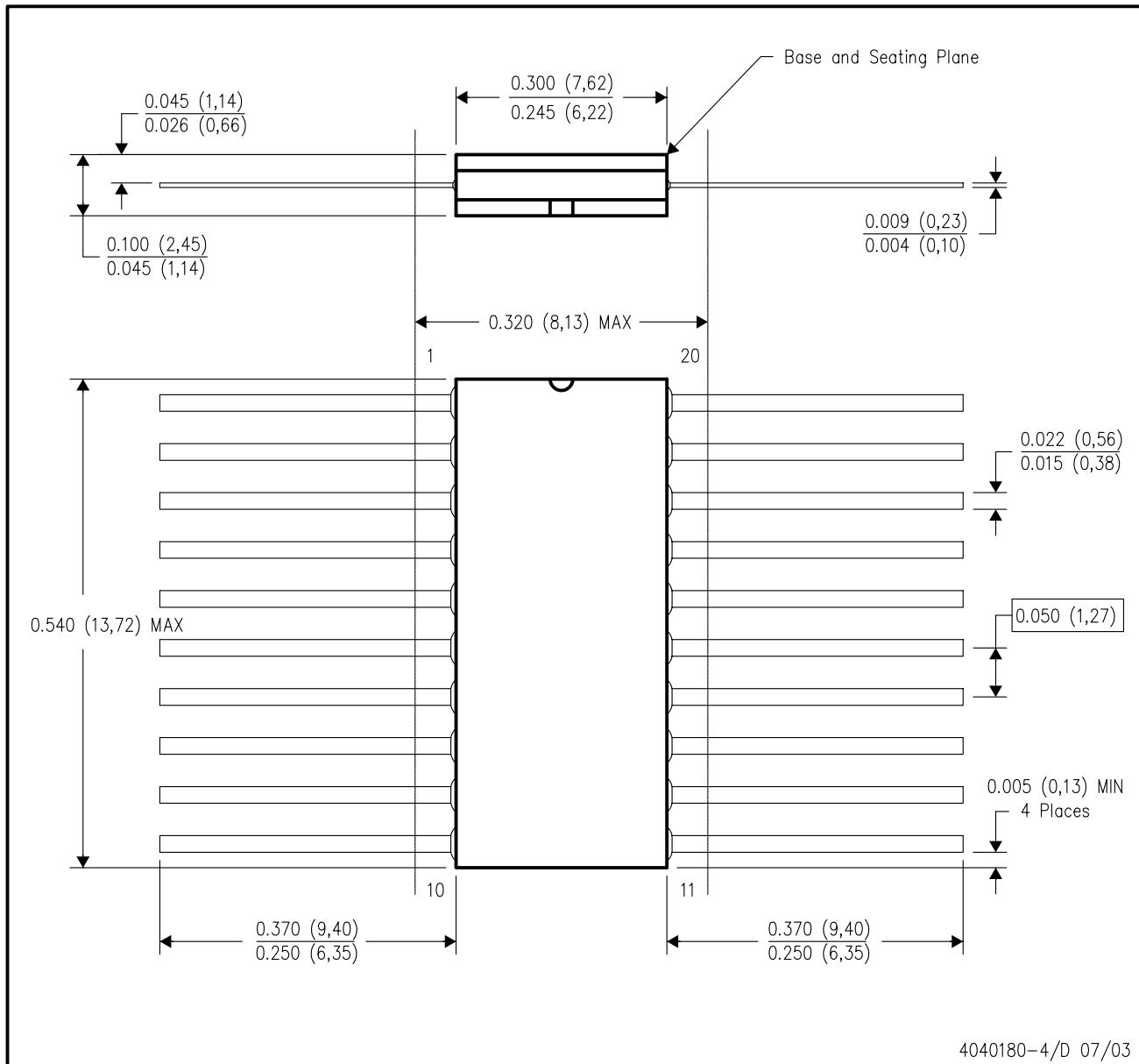


4040083/F 03/03

NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package is hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F20)

CERAMIC DUAL FLATPACK



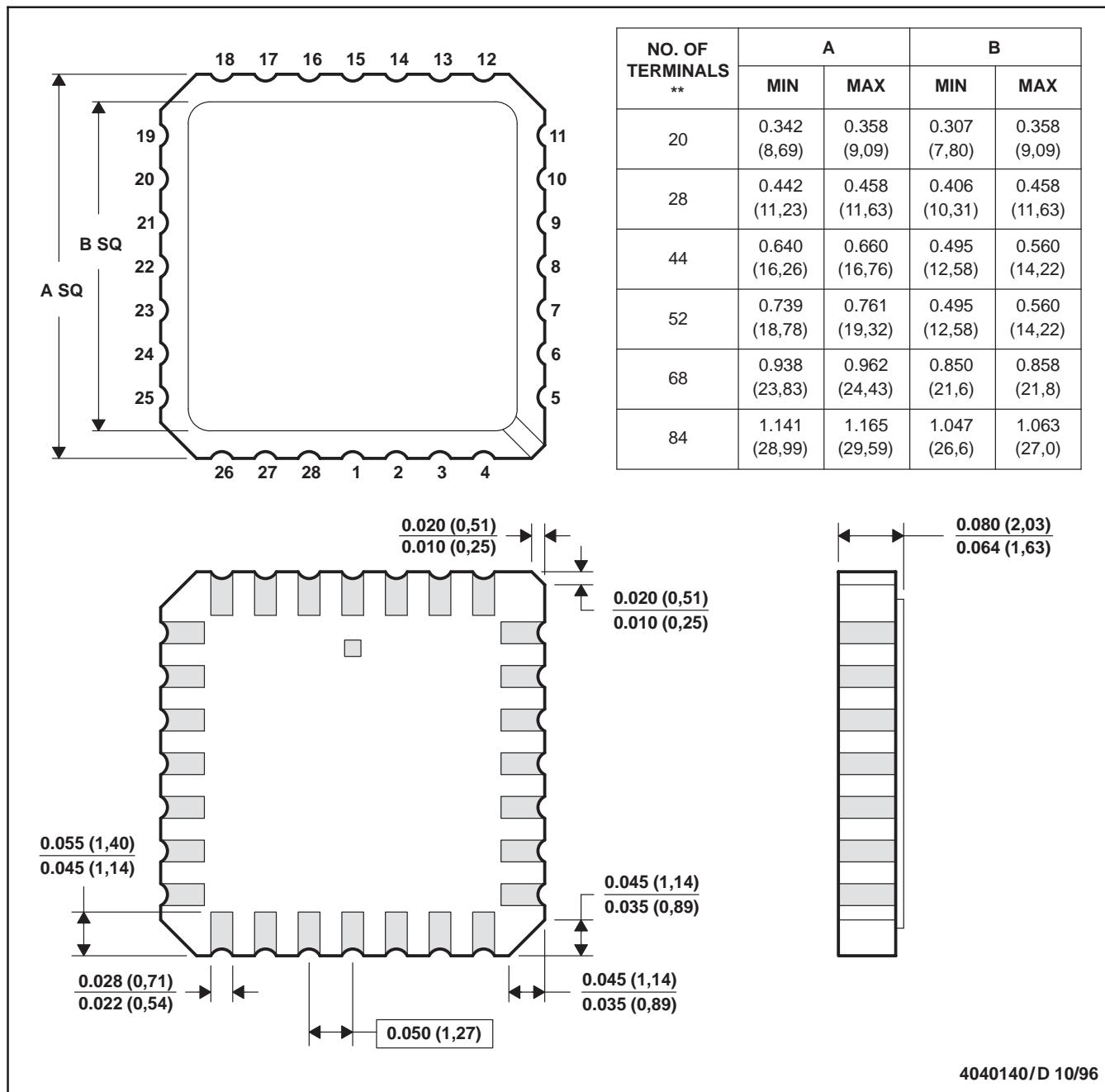
NOTES:

- All linear dimensions are in inches (millimeters).
- This drawing is subject to change without notice.
- This package can be hermetically sealed with a ceramic lid using glass frit.
- Index point is provided on cap for terminal identification only.
- Falls within Mil-Std 1835 GDFP2-F20

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004

N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



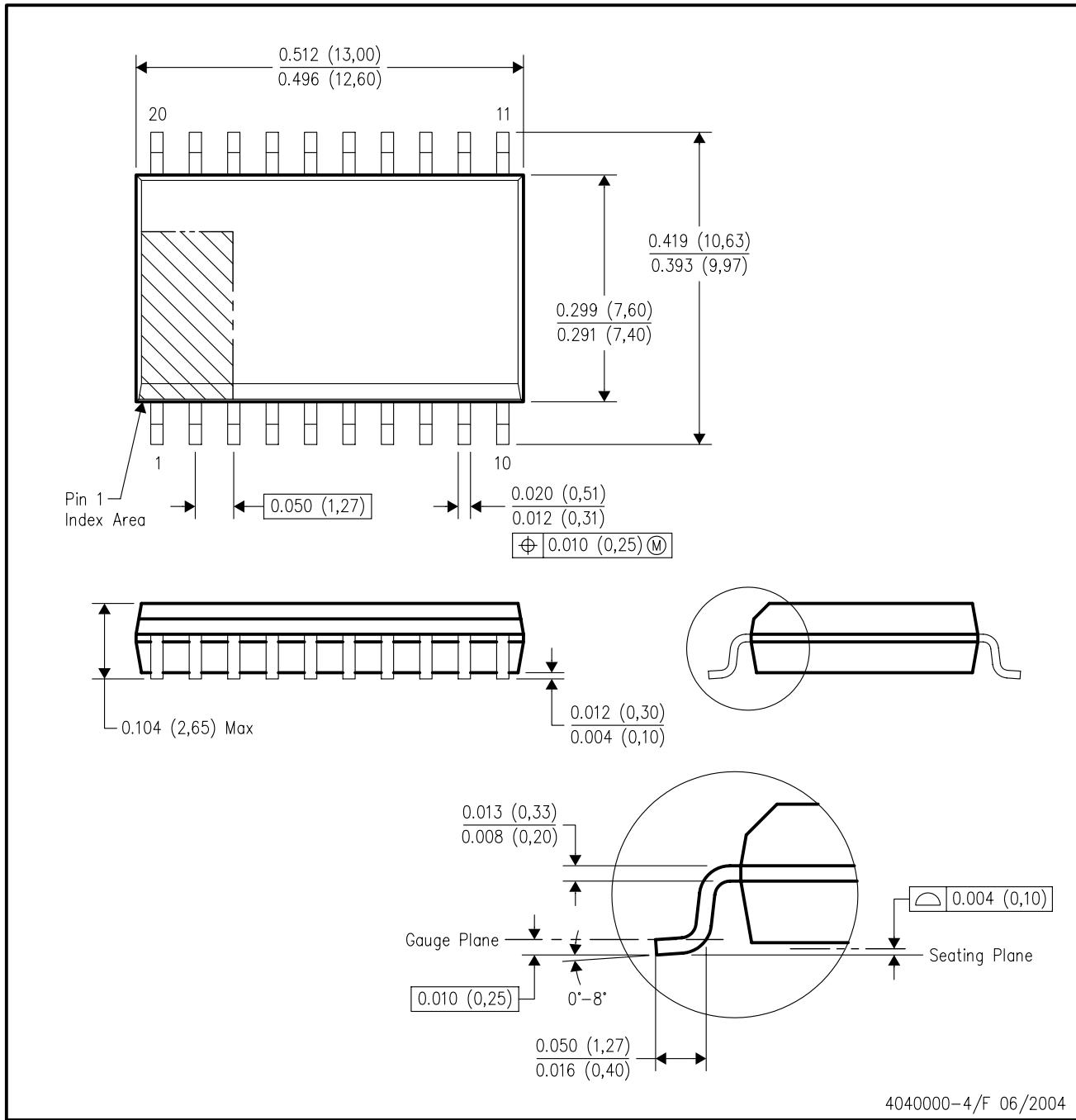
NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.

△ Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).

△ The 20 pin end lead shoulder width is a vendor option, either half or full width.

DW (R-PDSO-G20)

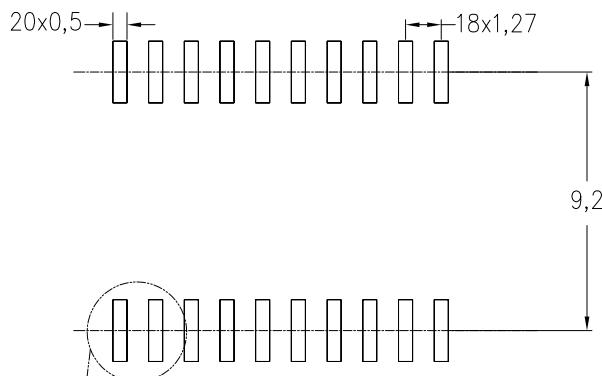
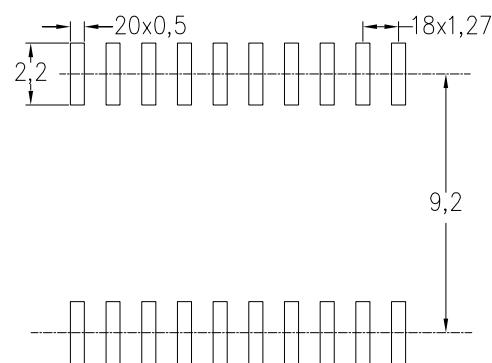
PLASTIC SMALL-OUTLINE PACKAGE



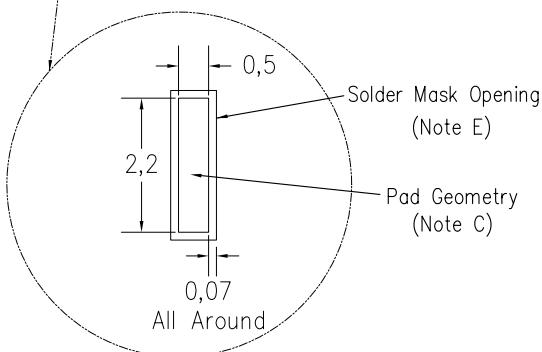
NOTES:

- All linear dimensions are in inches (millimeters).
- This drawing is subject to change without notice.
- Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- Falls within JEDEC MS-013 variation AC.

DW (R-PDSO-G20)

Example Board Layout
(Note C)Stencil Openings
(Note D)

Non Solder Mask Define Pad



4209202/A 01/08

NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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